

CBT3126

Quad FET bus switch

Rev. 04 — 12 October 2009

Product data sheet

1. General description

The CBT3126 is a quad FET bus switch with independent line switches. Each switch is disabled when the associated Output Enable (OE) input is LOW.

The CBT3126 is characterized for operation from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$.

2. Features

- Standard '126-type pinout
- Multiple package options
- $5\text{ }\Omega$ switch connection between two ports
- TTL-compatible input levels
- Minimal propagation delay through the switch
- Latch-up protection exceeds 500 mA per JEDEC standard JESD78 class II level A
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101C exceeds 1000 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

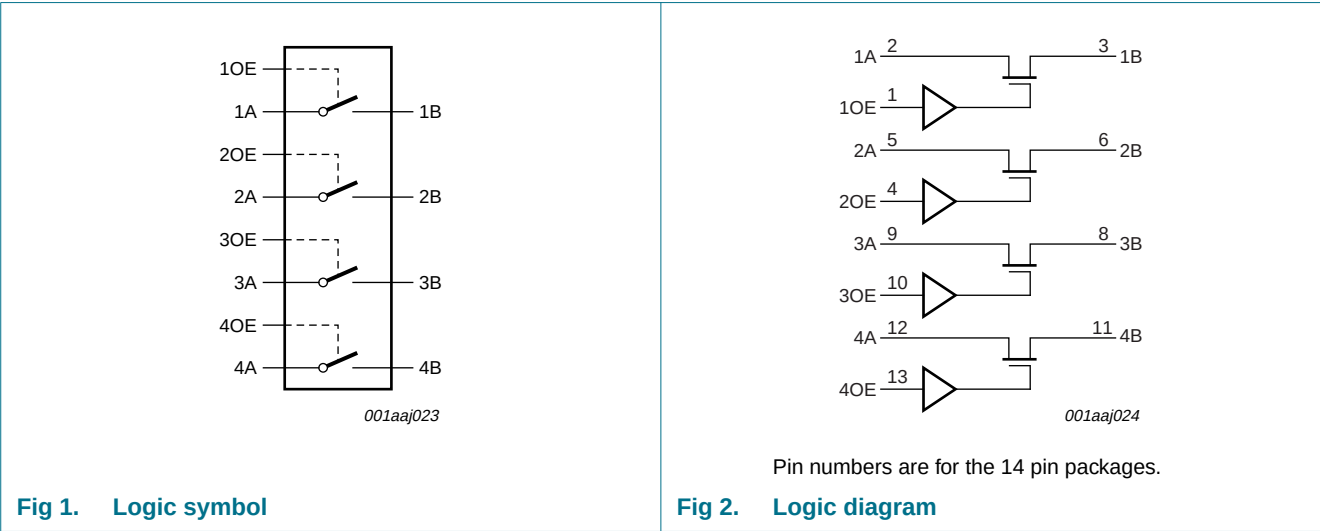
3. Ordering information

Table 1. Ordering information

Type number	Temperature range	Package		
		Name	Description	Version
CBT3126D	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
CBT3126DB	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
CBT3126PW	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
CBT3126DS	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	SSOP16 ^[1]	plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm	SOT519-1

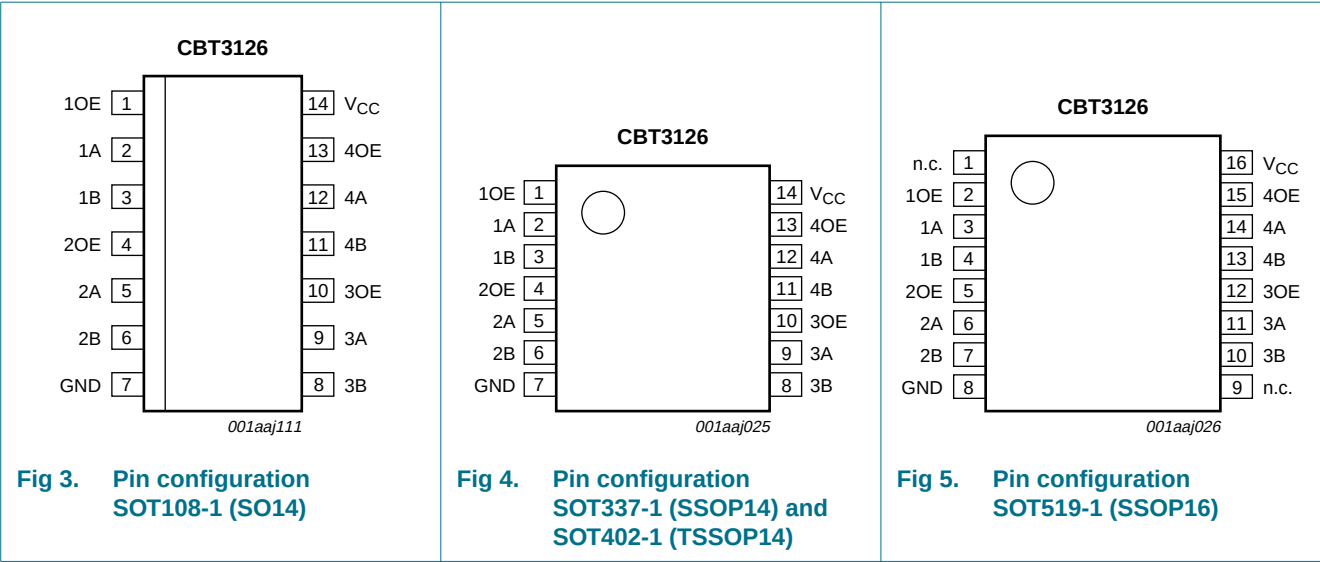
[1] Also known as QSOP16.

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin		Description
	SOT108-1 SOT337-1 and SOT402-1	SOT519-1	
1OE to 4OE	1, 4, 10, 13	2, 5, 12, 15	output enable input
1A to 4A,	2, 5, 9, 12	3, 6, 11, 14	A input/output
1B to 4B	3, 6, 8, 11	4, 7, 10, 13	B output/input

Table 2. Pin description ...continued

Symbol	Pin		Description
	SOT108-1 SOT337-1 and SOT402-1	SOT519-1	
GND	7	8	ground (0 V)
V _{CC}	14	16	positive supply voltage
n.c.	-	1, 9	not connected

6. Functional description

Table 3. Function selection

H = HIGH voltage level; L = LOW voltage level.

Inputs	Switch
nOE	
L	nA to nB disconnected
H	nA to nB connected

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		[1] -0.5	+7.0	V
I _{SW}	switch current	continuous current through each switch	-	128	mA
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	[2]		
		SO14 package	[3] -	500	mW
		SSOP14 and SSOP16 package	[4] -	500	mW
		TSSOP14 package	[4] -	500	mW

[1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

[2] The package thermal impedance is calculated from JE51-7.

[3] For SO14 package; P_{tot} derates linearly with 8 mW/K above 70 °C.

[4] For SSOP14, SSOP16 and TSSOP14 packages; P_{tot} derates linearly with 5.5 mW/K above 70 °C.

8. Recommended operating conditions

Table 5. Operating conditions

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		4.5	5.5	V
V _{IH}	HIGH-level input voltage		2.0	-	V
V _{IL}	LOW-level input voltage		-	0.8	V
T _{amb}	ambient temperature	operating in free-air	-40	+85	°C

9. Static characteristics

Table 6. Static characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$.

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{IK}	input clamping voltage	$V_{CC} = 4.5\text{ V}$; $I_I = -18\text{ mA}$	-	-	-1.2	V
V_{pass}	pass voltage	$V_I = V_{CC} = 5.0\text{ V}$; $I_{SW} = -100\text{ }\mu\text{A}$	-	3.8	-	V
I_I	input leakage current	$V_{CC} = 5.5\text{ V}$; $V_I = \text{GND}$ or 5.5 V	-	-	± 1	μA
I_{CC}	supply current	$V_{CC} = 5.5\text{ V}$; $I_{SW} = 0\text{ mA}$; $V_I = V_{CC}$ or GND	-	-	3	μA
ΔI_{CC}	additional supply current	control pins; per input; $V_{CC} = 5.5\text{ V}$; one input at 3.4 V , other inputs at V_{CC} or GND	^[2] -	-	2.5	mA
C_I	input capacitance	control pins; $V_I = 3\text{ V}$ or 0 V	-	1.7	-	pF
$C_{io(off)}$	off-state input/output capacitance	$V_O = 3\text{ V}$ or 0 V ; $\text{nOE} = V_{CC}$	-	3.4	-	pF
R_{ON}	ON resistance	$V_{CC} = 4.0\text{ V}$	^[3] -	-	-	-
		$V_I = 2.4\text{ V}$; $I_I = 15\text{ mA}$	-	16	22	Ω
		$V_{CC} = 4.5\text{ V}$	-	-	-	-
		$V_I = 0\text{ V}$; $I_I = 64\text{ mA}$	-	5	7	Ω
		$V_I = 0\text{ V}$; $I_I = 30\text{ mA}$	-	5	7	Ω
		$V_I = 2.4\text{ V}$; $I_I = 15\text{ mA}$	-	10	15	Ω

[1] All typical values are measured at $V_{CC} = 5\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

[2] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND .

[3] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. ON resistance is determined by the lowest voltage of the two (A or B) terminals.

10. Dynamic characteristics

Table 7. Dynamic characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; $V_{CC} = 4.5\text{ V}$ to 5.5 V ; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	Min	Max	Unit
t_{pd}	propagation delay	nA to nB or nB to nA; see Figure 6	^{[1][2]} -	0.25	ns
t_{en}	enable time	nOE to nA or nB; see Figure 7	^[2] 1.6	4.5	ns
t_{dis}	disable time	nOE to nA or nB; see Figure 7	^[2] 1.0	5.4	ns

[1] This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical ON resistance of the switch and a load capacitance, when driven by an ideal voltage source (zero output impedance).

[2] t_{PLH} and t_{PHL} are the same as t_{pd} ;
 t_{PZL} and t_{PZH} are the same as t_{en} ;
 t_{PLZ} and t_{PHZ} are the same as t_{dis} .

11. AC waveforms

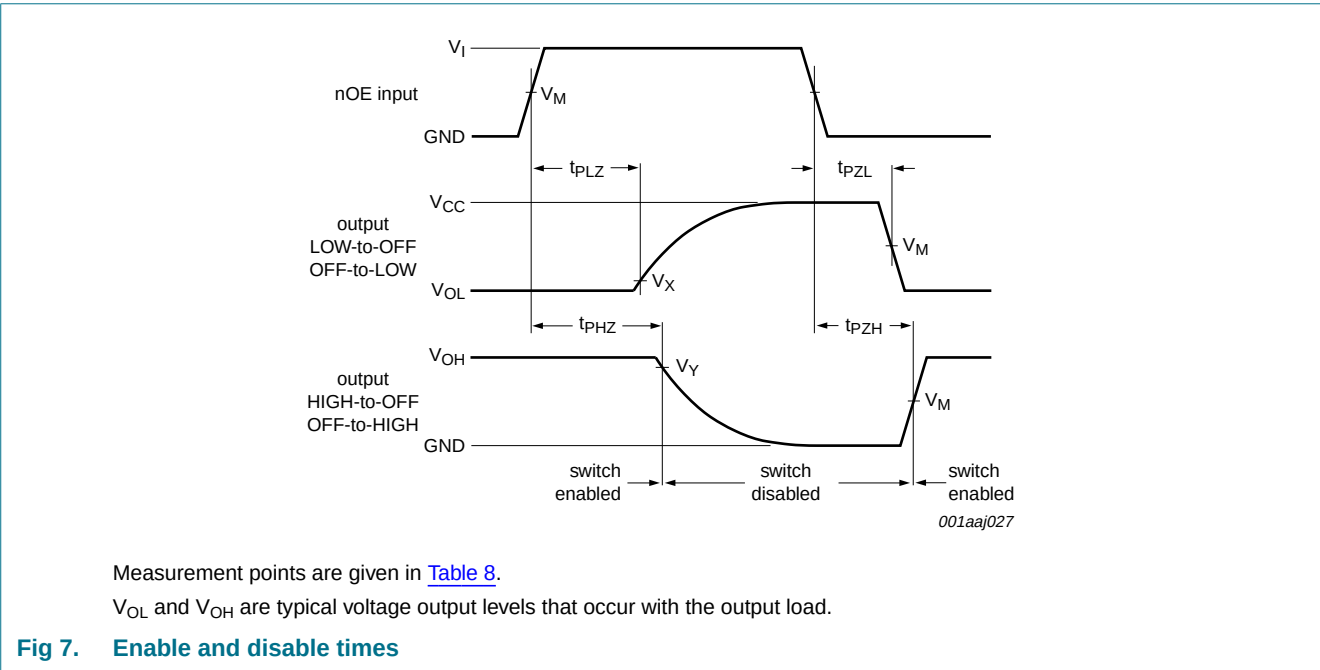
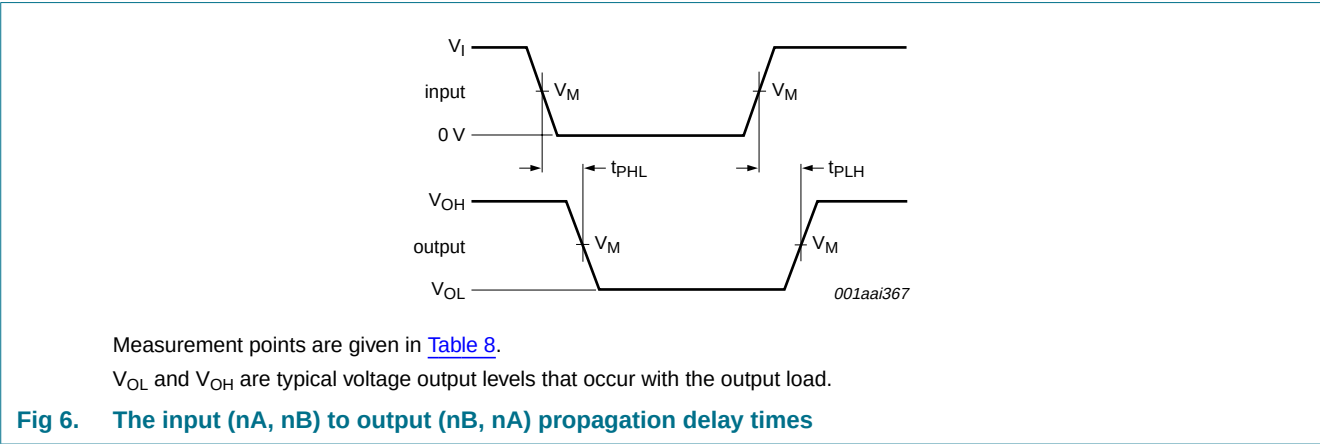
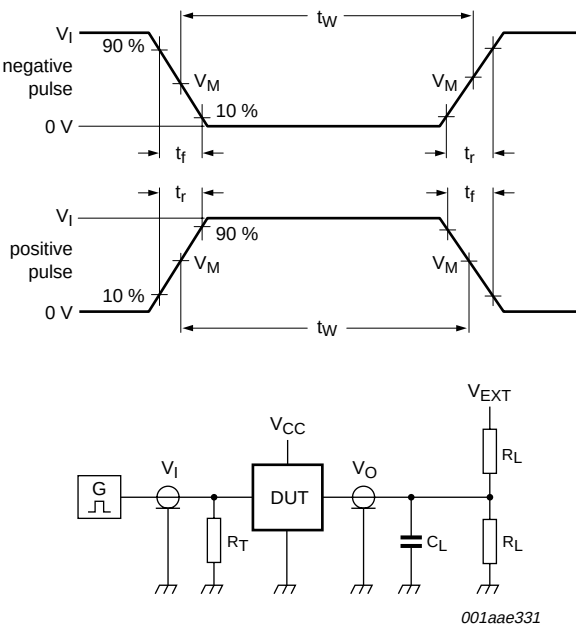


Table 8. Measurement points

Input	Output		
V_M	V_M	V_X	V_Y
1.5 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$

12. Test information



Test data is given in [Table 9](#).
Definitions for test circuit:
 R_L = Load resistance.
 C_L = Load capacitance including jig and probe capacitance.
 R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.
 V_{EXT} = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
V_{CC}	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
4.5 V to 5.5 V	GND to 3.0 V	≤ 2.5 ns	50 pF	500 Ω	open	7.0 V	open

13. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1

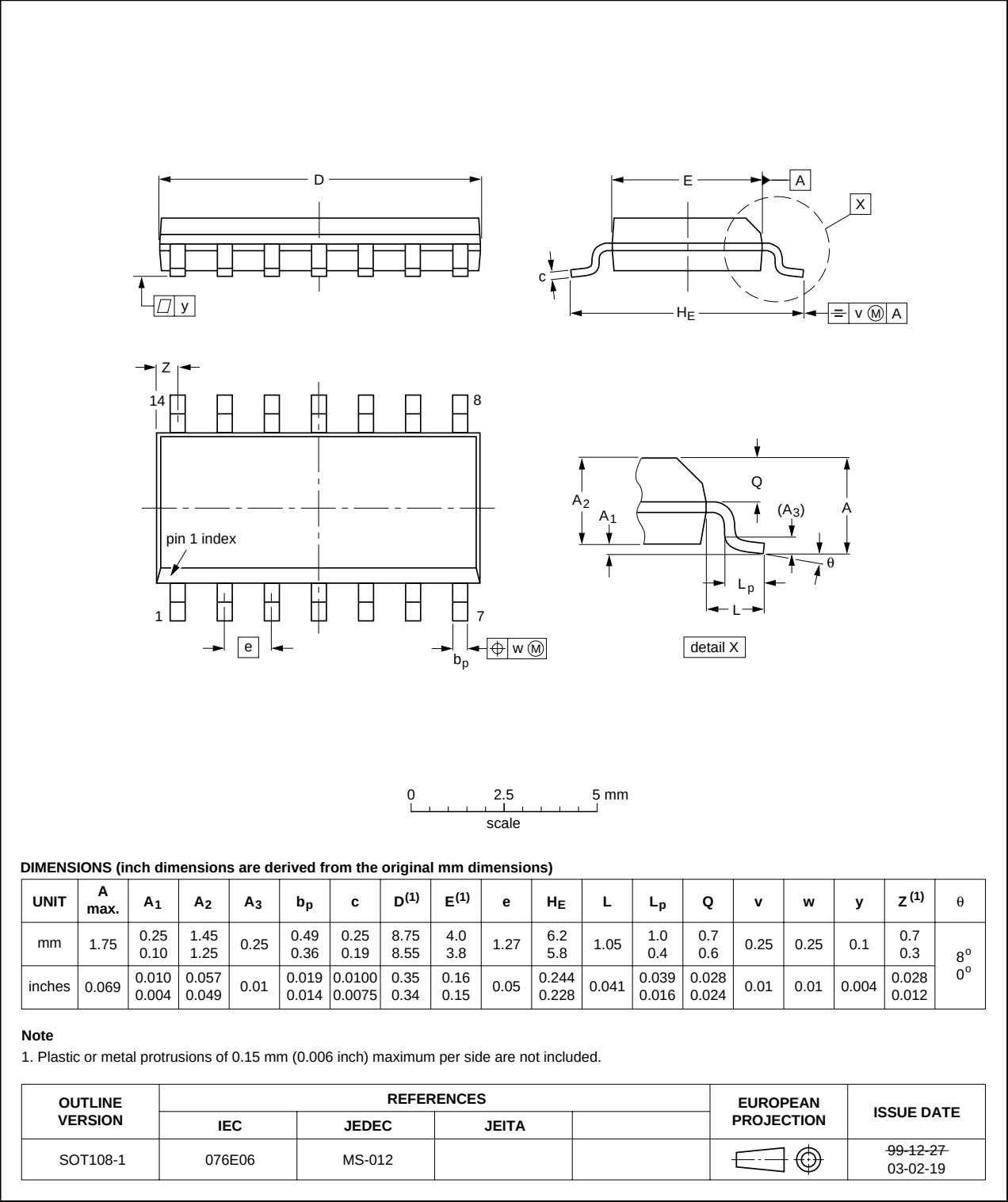


Fig 9. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

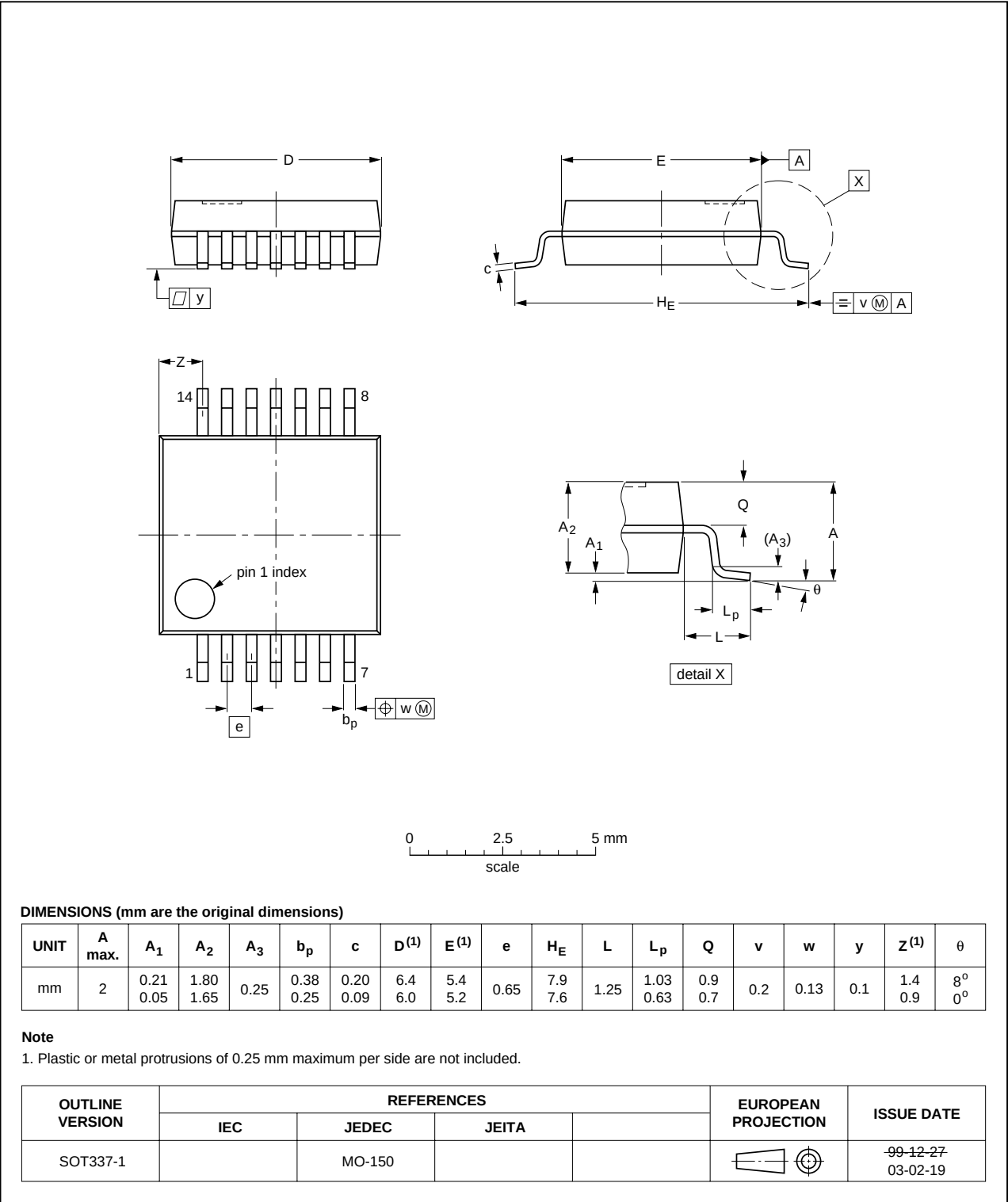


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

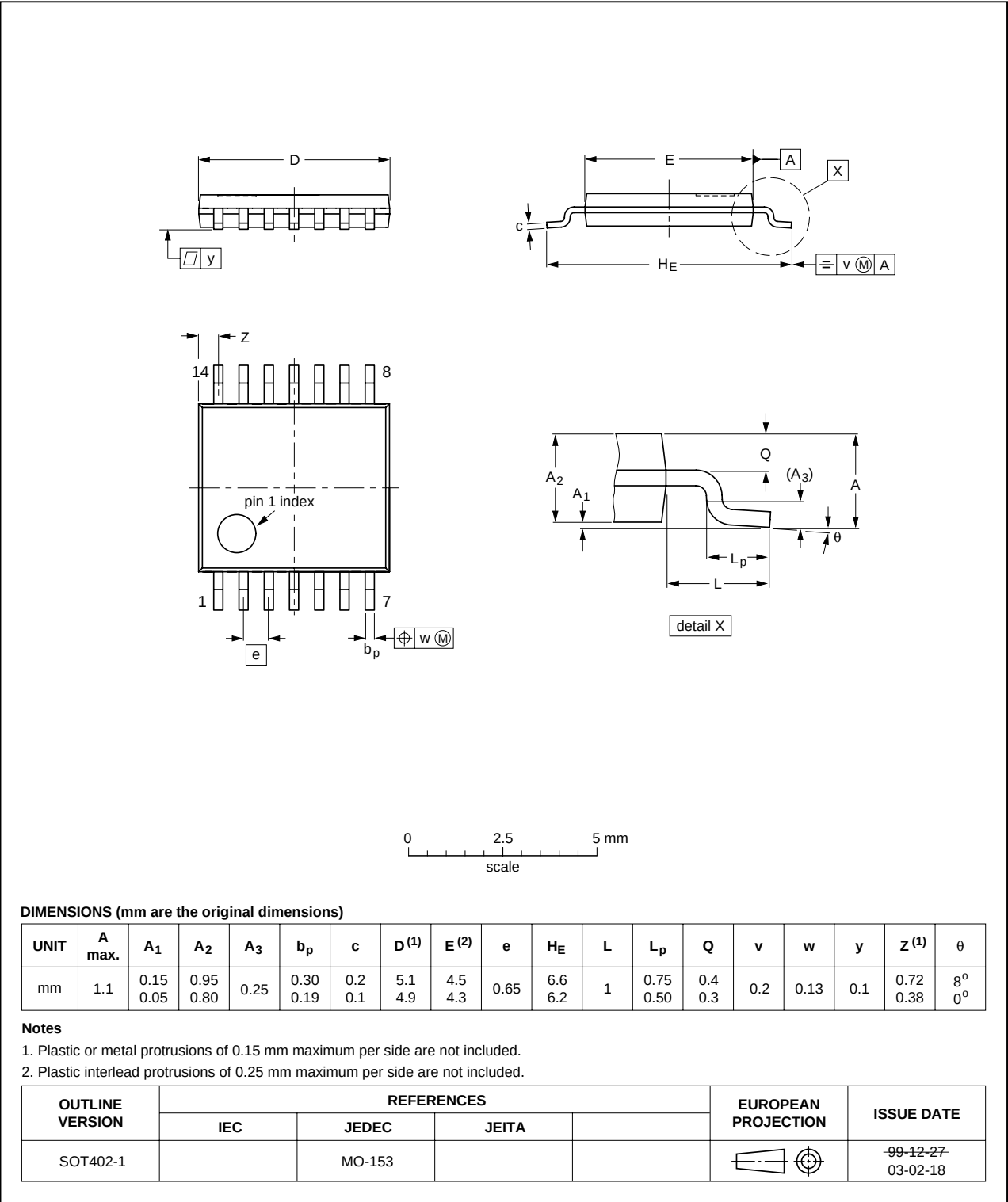


Fig 11. Package outline SOT402-1 (TSSOP14)

SSOP16: plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm SOT519-1

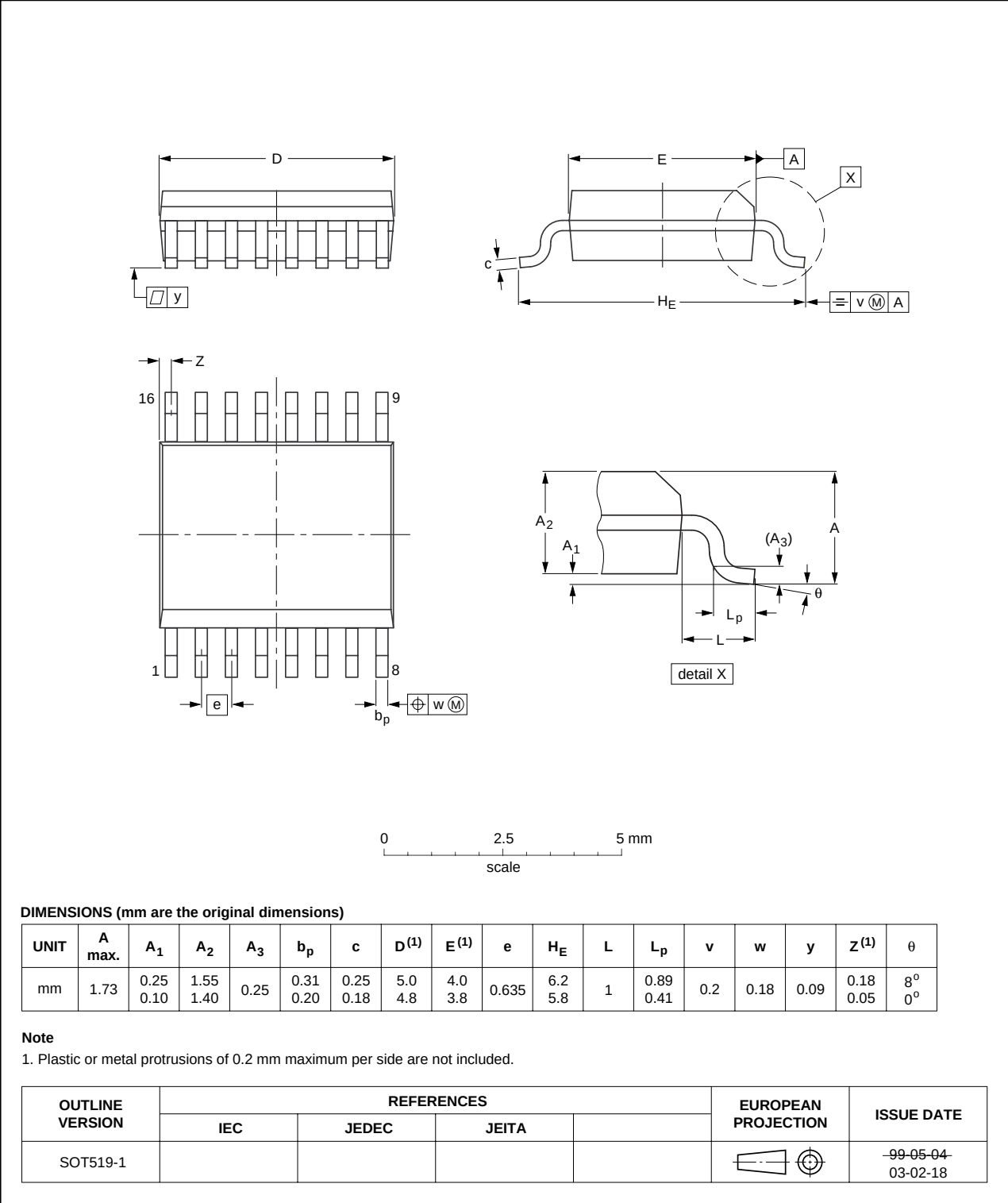


Fig 12. Package outline SOT519-1 (SSOP16)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CBT3126_4	20091012	Product data sheet	-	CBT3126_3
Modifications:	• Section 7 "Limiting values" changed I_{CC} to I_{SW} .			
CBT3126_3	20081209	Product data sheet	-	CBT3126_2
CBT3126_2	20081023	Product data sheet	-	CBT3126_1
CBT3126_1	20011212	Product data sheet	-	-

16. Legal information

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Contents

1	General description	1
2	Features	1
3	Ordering information	1
4	Functional diagram	2
5	Pinning information	2
5.1	Pinning	2
5.2	Pin description	2
6	Functional description	3
7	Limiting values	3
8	Recommended operating conditions	3
9	Static characteristics	4
10	Dynamic characteristics	4
11	AC waveforms	5
12	Test information	6
13	Package outline	7
14	Abbreviations	11
15	Revision history	11
16	Legal information	12
16.1	Data sheet status	12
16.2	Definitions	12
16.3	Disclaimers	12
16.4	Trademarks	12
17	Contact information	12
18	Contents	13

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